

Title (en)

Method of manufacturing an electronic component comprising an integrated circuit and a winding assembly

Title (de)

Herstellungsmethode für ein einen integrierten Schaltkreis und eine Wicklungsanordnung enthaltendes elektronisches Bauteil

Title (fr)

Procédé de fabrication d'un composant électronique comportant un circuit intégré et un ensemble d'enroulement

Publication

**EP 1786004 A2 20070516 (EN)**

Application

**EP 06122211 A 20061012**

Priority

- EP 05110652 A 20051111
- EP 06122211 A 20061012

Abstract (en)

A method of manufacturing an electronic component comprising an integrated circuit (1) and a core (2), includes the steps of providing the integrated circuit having at least two accessible contacts (12,14), providing the core, assembling the integrated circuit and the core together by means of an adhesive substance (4), winding a wire (30) on the core in order to produce a winding (3), bonding or soldering a first end (31) of the wire to a first one of said contacts and bonding or soldering a second end (32) of the wire to a second one of said contacts.

IPC 8 full level

**H01F 27/40** (2006.01); **H01F 41/06** (2006.01)

CPC (source: EP)

**H01F 27/40** (2013.01); **H01F 41/076** (2016.01); **H01F 17/045** (2013.01)

Citation (applicant)

- EP 0405671 A1 19910102 - PHILIPS NV [NL]
- EP 0573469 B1 19940727 - GUSTAFSON AKE [CH]
- US 4860433 A 19890829 - MIURA NORIO [JP]
- JP 2005130055 A 20050519 - CITIZEN WATCH CO LTD
- US 2002180602 A1 20021205 - YOAKUM JAY [US]

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

**EP 1786004 A2 20070516; EP 1786004 A3 20120711; EP 1786004 B1 20150520**

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